

C1206C279B2TACTU

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Aliases (C1206C279B2TAC7800) SMD Comm X8G HT150C, Ceramic, 2.7 pF, +/-0.1 pF, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm



Click here for the 3D model.

General Information	
Series	SMD Comm X8G HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	15 mg
Shelf Life	78 Weeks
MSL	1

nensions		Specificatio
p Size	1206	Capacitance
	3.2mm +/-0.2mm	Measureme
	1.6mm +/-0.2mm	Tolerance
	0.78mm +/-0.10mm	Voltage DC
	1.5mm MIN	Dielectric W
	0.5mm +/-0.25mm	Temperatur
		Temp. Coef

Packaging Specifications	
Packaging	

Packaging Quantity

Dim Chip L W T S B

> T&R, 180mm, Plastic Tape 4000

Specifications	
Capacitance	2.7 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	+/-0.1 pF
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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